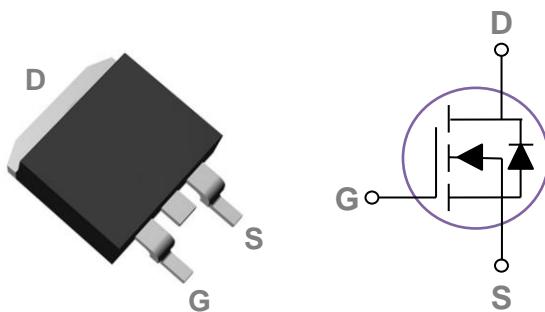


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO263 Pin Configuration



BVDSS	RDS(ON)	ID
80V	3.4mΩ	165A

### Features

- 80V, 165A,  $RDS(ON) = 3.4m\Omega @ VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications
- Quick Charger

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	80	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	165	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	105	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	660	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	520	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	102	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	240	W
	Power Dissipation – Derate above $25^\circ C$	1.92	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	0.52	$^\circ C/W$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	80	---	---	V
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=64\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=85^\circ\text{C}$	---	---	10	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

**On Characteristics**

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=20\text{A}$	---	2.8	3.4	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	2	3	4	V
$\text{gfs}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=3\text{A}$	---	13	---	S

**Dynamic and switching Characteristics**

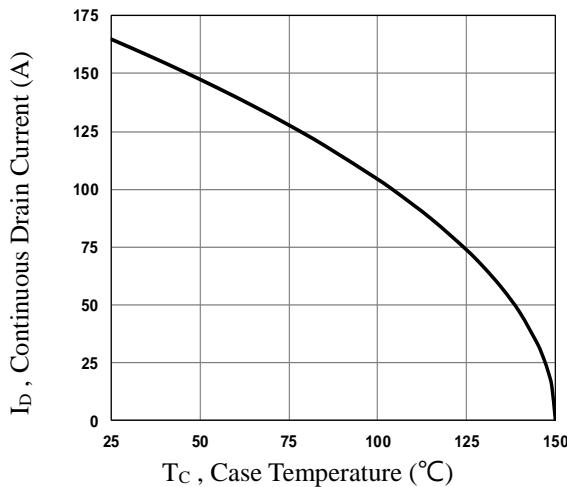
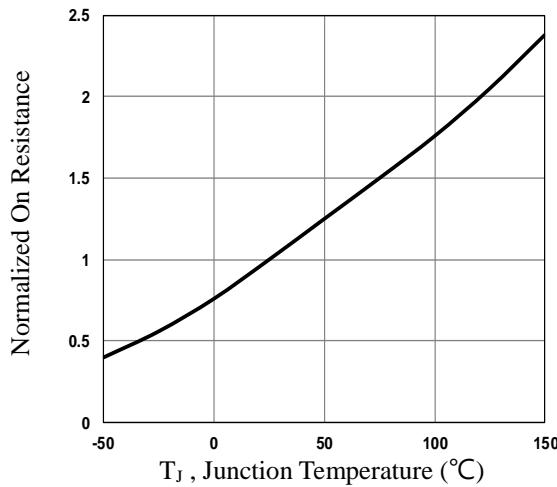
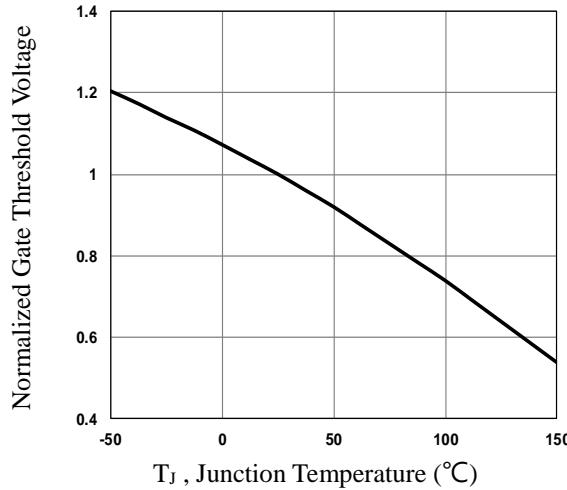
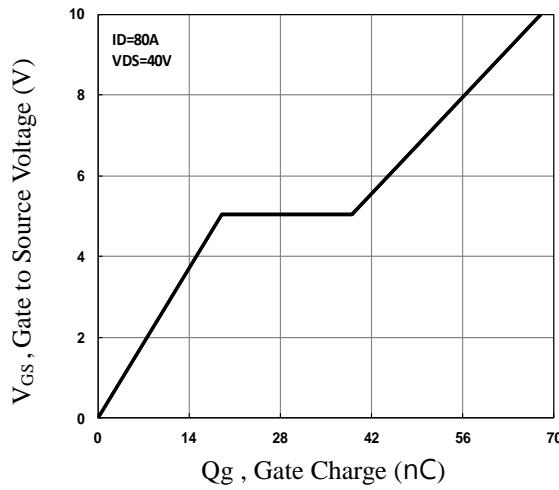
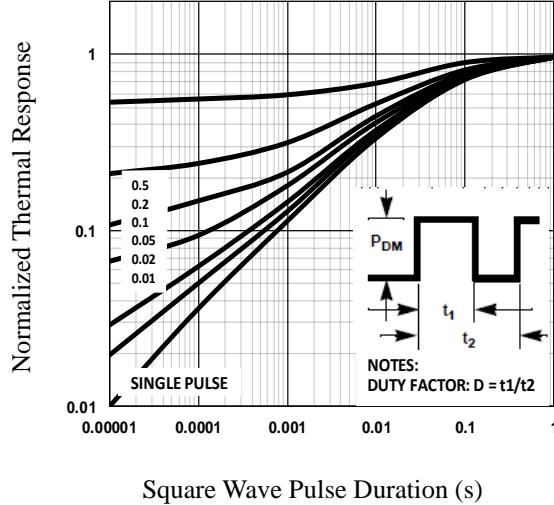
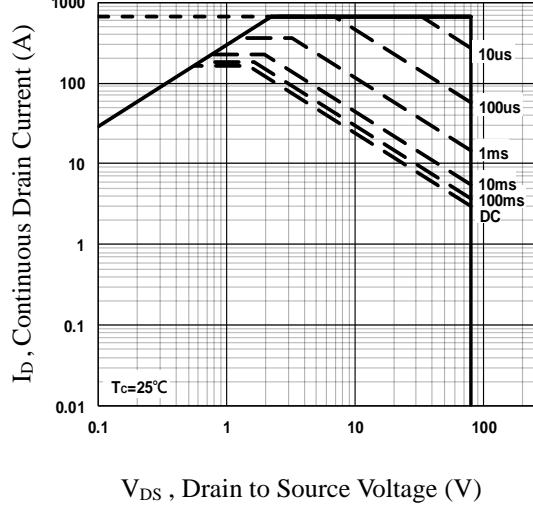
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=40\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=80\text{A}$	---	68	100	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	19	30	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	20	30	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=40\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=6\Omega$ $I_{\text{D}}=80\text{A}$	---	30	45	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	25	40	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	45	70	
$T_f$	Fall Time <sup>3, 4</sup>		---	25	40	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=40\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	4600	6900	pF
$C_{\text{oss}}$	Output Capacitance		---	990	1500	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	16	24	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.8	---	$\Omega$

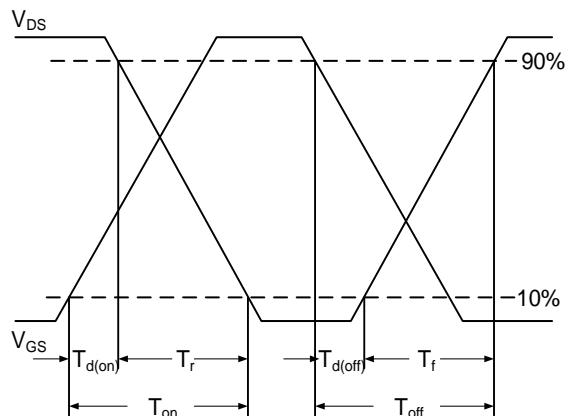
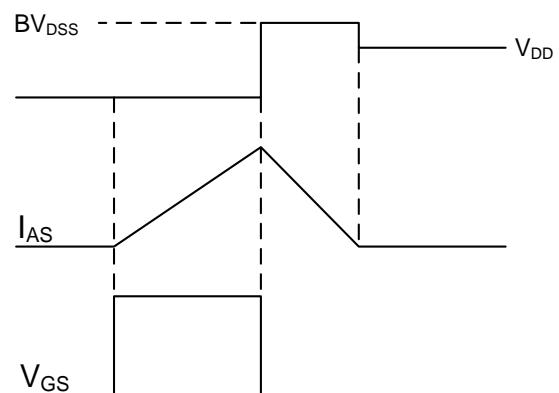
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	165	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	330	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_R=50\text{V}$ , $I_s=10\text{A}$ $di/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	70	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge		---	160	---	nC

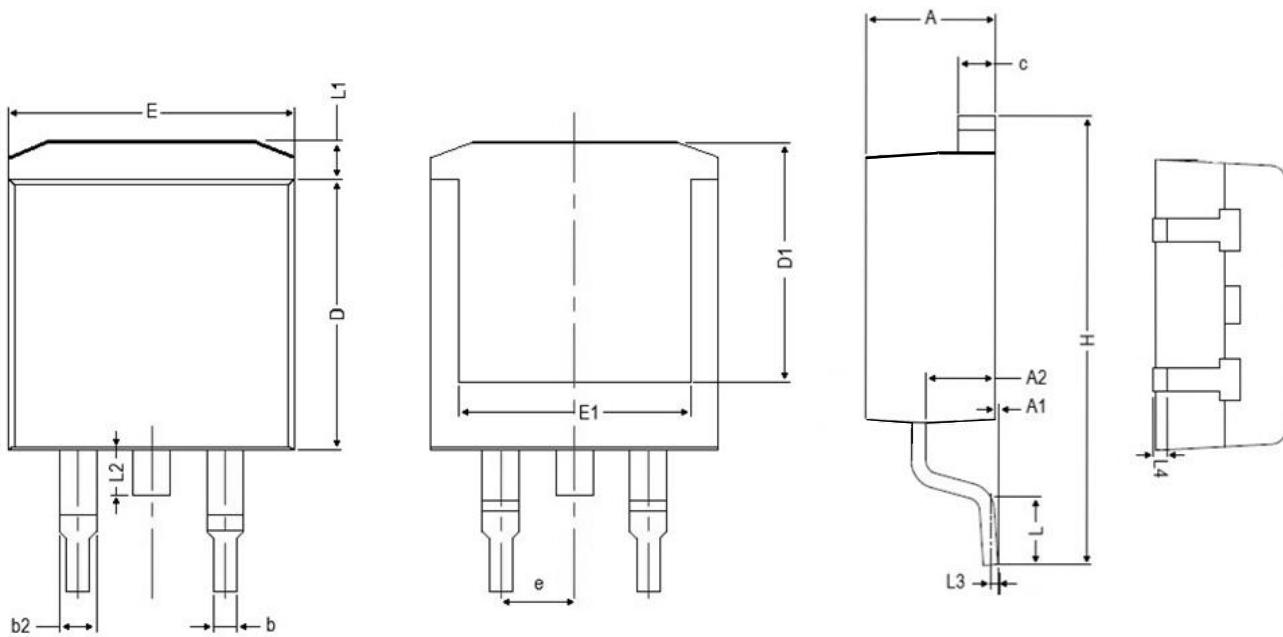
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=102\text{A}$ ,  $R_{\text{G}}=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. TC**

**Fig.2 Normalized RDSON vs. TJ**

**Fig.3 Normalized Vth vs. TJ**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 EAS Waveform**

## TO263 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	4.850	4.250	0.191	0.167
A1	0.250	0.000	0.001	0.000
A2	2.900	2.350	0.114	0.093
b	0.950	0.700	0.037	0.028
b2	1.600	1.000	0.063	0.039
c	1.450	1.200	0.057	0.047
D	9.500	8.350	0.374	0.329
D1	9.150	6.400	0.360	0.252
E	10.500	9.600	0.413	0.378
E1	8.900	7.500	0.350	0.295
e	2.540 BSC		0.100 BSC	
H	15.900	14.600	0.626	0.575
L	2.800	2.000	0.110	0.079
L1	1.700	1.150	0.067	0.045
L2	2.100	1.400	0.083	0.055
L3	0.250 BSC		0.010 BSC	
L4	0.750	0.200	0.030	0.001